



(51) International Patent Classification:

B32B 3/30 (2006.01) *B32B 33/00* (2006.01)
B32B 7/02 (2006.01) *B65D 75/62* (2006.01)
B32B 15/20 (2006.01) *B32B 15/08* (2006.01)
B32B 27/08 (2006.01)

(21) International Application Number:

PCT/SG2012/000385

(22) International Filing Date:

15 October 2012 (15.10.2012)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

201107612-2 18 October 2011 (18.10.2011) SG

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY,
BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,

HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,
KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD,
ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,
NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU,
RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ,
TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA,
ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ,
UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,
TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV,
MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— of inventorship (Rule 4.17(iv))

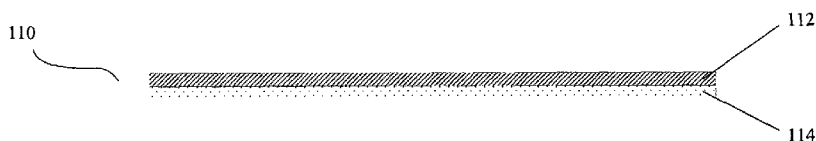
Published:

— with international search report (Art. 21(3))

(88) Date of publication of the international search report:

16 October 2014

(54) Title: PACKAGING MATERIAL, PACKAGE PRODUCED THEREFROM AND METHOD FOR CONSTRUCTING THE PACKAGE



(57) Abstract: The present invention provides packaging material for making packages, comprising a breakable film; and a substrate on which the breakable film is positioned, wherein the substrate comprises a chemically resistant and non-heat sealable (NHS) layer having a first surface and a second surface, and a heat sealable (HS) layer bonded to the first surface of the NHS layer, and the breakable film is laminated onto the second surface of the NHS layer, and wherein at least one die cut line to define a preformed hole is formed through the NHS and HS layers. The invention also provides a package produced therefrom and a method for constructing the package.

